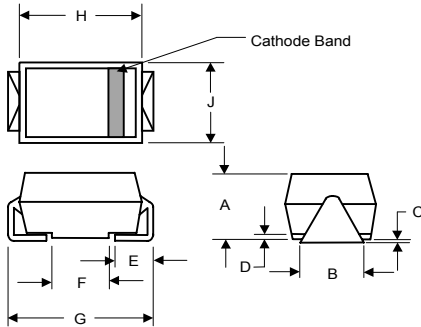




# FS2A THRU FS2M

**SURFACE MOUNT FAST RECOVERY RECTIFIER**  
 Reverse Voltage - 50 to 1000 Volts Forward Current -2.0 Ampere

## DO-214AC (HSMA) (High Profile)



DIM	DIMENSIONS				NOTE
	INCHES		MM		
	MIN	MAX	MIN	MAX	
A	.078	.116	1.98	2.95	
B	.067	.089	1.70	2.25	
C	.002	.008	.05	.20	
D	—	.02	—	.51	
E	.035	.065	.89	1.40	
F	.065	.096	1.65	2.45	
G	.205	.224	5.21	5.69	
H	.160	.180	4.06	4.57	
J	.100	.112	2.57	2.84	

## FEATURES

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Low reverse leakage
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed: 250°C/10 seconds at terminals
- ◆ Glass passivated chip junction

## MECHANICAL DATA

**Case** : JEDEC DO-214AC molded plastic body over passivated chip  
**Terminals** : Solder plated, solderable per MIL-STD-750, Method 2026  
**Polarity** : Color band denotes cathode end  
**Mounting Position** : Any  
**Weight** : 0.002 ounce, 0.07 grams

## MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.  
 Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

MDD Catalog Number	SYMBOLS	FS2A	FS2B	FS2D	FS2G	FS2J	FS2K	FS2M	UNITS
Maximum repetitive peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	VOLTS
Maximum RMS voltage	$V_{RMS}$	35	70	140	280	420	560	700	VOLTS
Maximum DC blocking voltage	$V_{DC}$	50	100	200	400	600	800	1000	VOLTS
Maximum average forward rectified current at $T_L=90^\circ\text{C}$	$I_{(AV)}$	2.0							Amp
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	50.0							Amps
Maximum instantaneous forward voltage at 2.0A	$V_F$	1.3							Volts
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=100^\circ\text{C}$	$I_R$	5.0 50.0							$\mu\text{A}$
Maximum reverse recovery time (NOTE 1)	$t_{rr}$	150			250		500		ns
Typical junction capacitance (NOTE 2)	$C_J$	50.0							pF
Typical thermal resistance (NOTE 3)	$R_{\theta JA}$	15.0							$^\circ\text{C/W}$
Operating junction and storage temperature range	$T_J, T_{STG}$	-50 to +150							$^\circ\text{C}$

**Note:** 1. Reverse recovery condition  $I_F=0.5\text{A}, I_R=1.0\text{A}, I_{rr}=0.25\text{A}$   
 2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.  
 3. P.C.B. mounted with 0.2x0.2" (5.0x5.0mm) copper pad areas

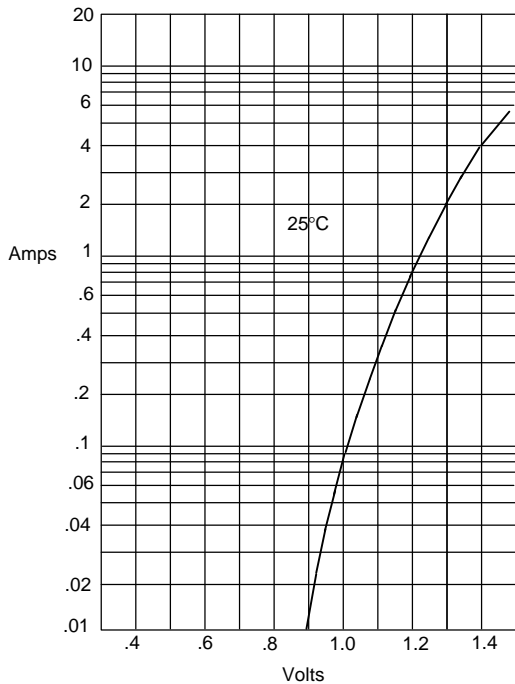


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# RATINGS AND CHARACTERISTIC CURVES FS2A THRU FS2M

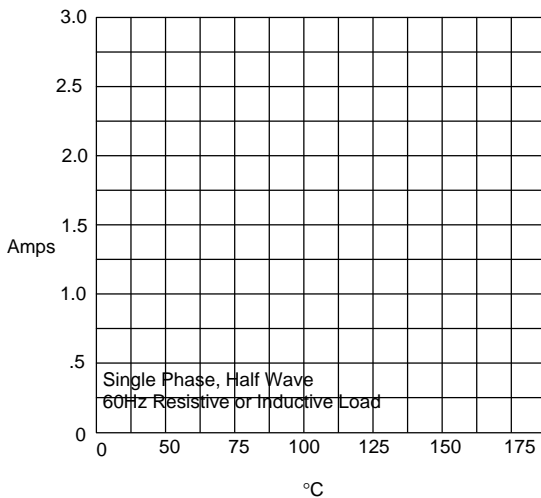
Figure 1

Typical Forward Characteristics



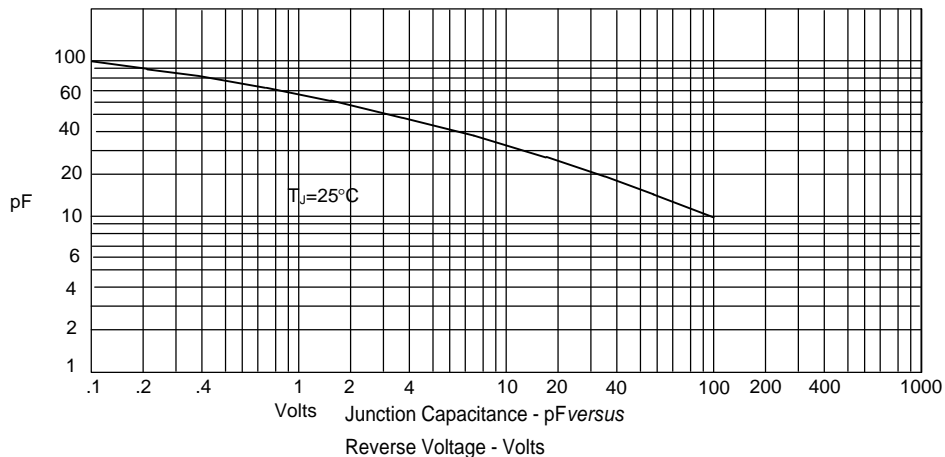
Instantaneous Forward Current - Amperes versus  
Instantaneous Forward Voltage - Volts

Figure 2  
Forward Derating Curve



Average Forward Rectified Current - Amperes versus  
Ambient Temperature - °C

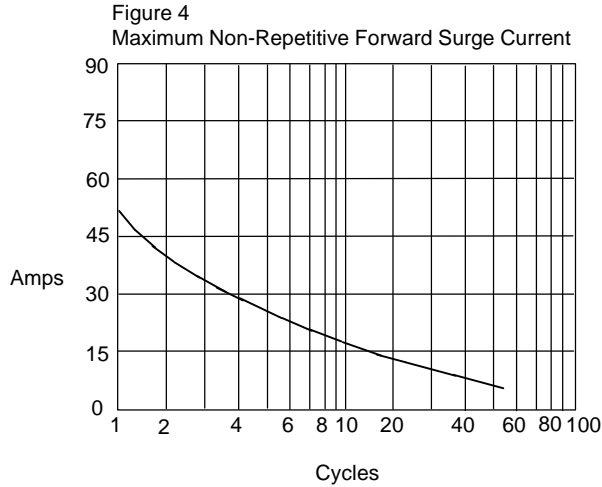
Figure 3  
Junction Capacitance



The cruve graph is for reference only, can't be the basis for judgment(曲线图仅供参考!)

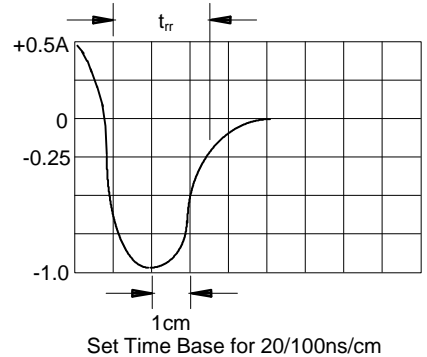
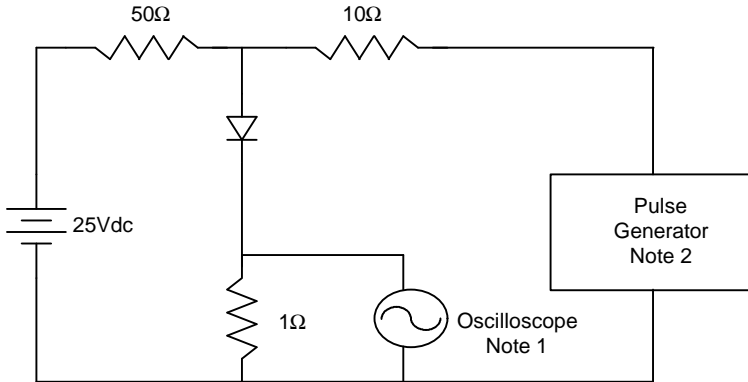


# RATINGS AND CHARACTERISTIC CURVES FS2A THRU FS2M



Peak Forward Surge Current - Amperes versus  
Number Of Cycles At 60Hz - Cycles

Figure 5  
Reverse Recovery Time Characteristic And Test Circuit Diagram



Notes:

1. Rise Time = 7ns max.  
Input impedance = 1 megohm, 22pF
2. Rise Time = 10ns max.  
Source impedance = 50 ohms
3. Resistors are non-inductive

The cruve graph is for reference only, can't be the basis for judgment(曲线图仅供参考)!

